PCT WORLD INTELLECTUAL PROPERTY ORGANIZATION
International Bureau

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification 7 :
H01L 21/00 // F26B 21/14

A1

(11) International Publication Number: **WO 00/22654**

(43) International Publication Date: 20 April 2000 (20.04.00)

(21) International Application Number: PCT/US99/22483

(22) International Filing Date: 28 September 1999 (28.09.99)

(30) Priority Data:

60/103,802	9 October 1998 (09.10.98)	US
09/227,637	8 January 1999 (08.01.99)	US

(71) Applicant: SCP GLOBAL TECHNOLOGIES, a division of PRECO, INC. [US/US]; 400 Benjamin Lane, Boise, ID 83704 (US).

(72) Inventors: TAMER, Elsawy; IBM Microelectronics, 1000 River Road, Mail Stop 967–K, Essex Junction, VT 05452 (US). HALL, R., Mark; 2160 N. Amethyst, Meridian, ID 83642 (US). BUTLER, Josh; 1054 N. Nugget Street, Kuna, ID 83634 (US).

(74) Agents: FROST, Kathleen, A. et al.; Limbach & Limbach L.L.P., 2001 Ferry Building, San Francisco, CA 94121 (US).

(81) Designated States: AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CR, CU, CZ, DE, DK, DM, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZA, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

Published
With international search report.
Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.

(54) Title: WAFER CLEANING AND VAPOR DRYING SYSTEM AND METHOD

(57) Abstract

The present invention is a method and system for treating and drying the surface of an object especially a semiconductor wafer. According to the described method, with a wet object positioned in a vessel, a drying vapor of isopropyl alcohol is introduced into the vessel. The drying vapor condenses on the surface of the object and reduces the surface tension of the residual process fluid, causing the residual process fluid to flow off of the surface. Wet processing of the object like HF cleaning and/or deionized water rinsing with subsequent evacuation of process fluid is carried out in the vessel prior to introduction of the drying vapor.

